

/ Descriptions

SOT-23 NPN Silicon NPN transistor in a SOT-23 Plastic Package.

/ Features

 , KTA1505
Excellent hFE linearity, complementary pair with KTA1505.

/ Applications

General amplifier and switching application.

/ Equivalent Circuit



/ Pinning



PIN 1 Base PIN 2 : Emitter PIN 3 Collector

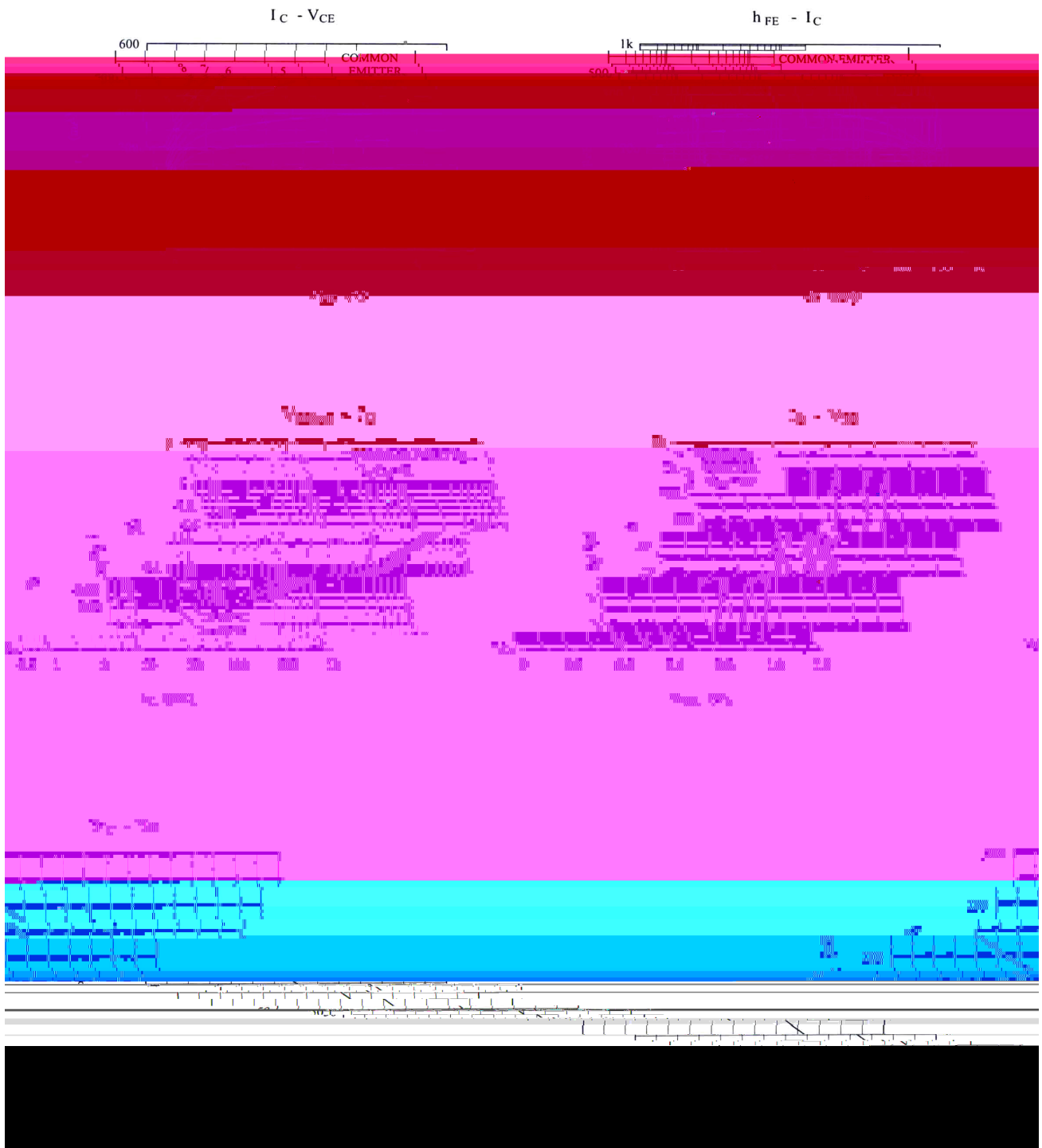
/ h_{FE} Classifications & Marking

h _{FE} Classifications Symbol	O	Y	GR
h _{FE} Range	70 140	120 240	200 400
Marking	HWO	HWY	HWG

Symbol	Rating	Unit
V_{CBO}	35	V
V_{CEO}	30	V
V_{EBO}	5.0	V
I_C	500	mA
I_B	50	mA
P_C	150	mW
T_j	150	
T_{stg}	-55 150	

Conditions	Min	Typ	Max	Unit
$I_E=0$			0.1	μA
$I_C=0$			0.1	μA
$I_C=100mA$	70		400	
$I_C=400mA$	25			
$I_B=10mA$		0.1	0.25	V
$I_C=100mA$		0.8	1.0	V
$I_C=20mA$		300		MHz
$f=1.0MHz$		7.0		pF

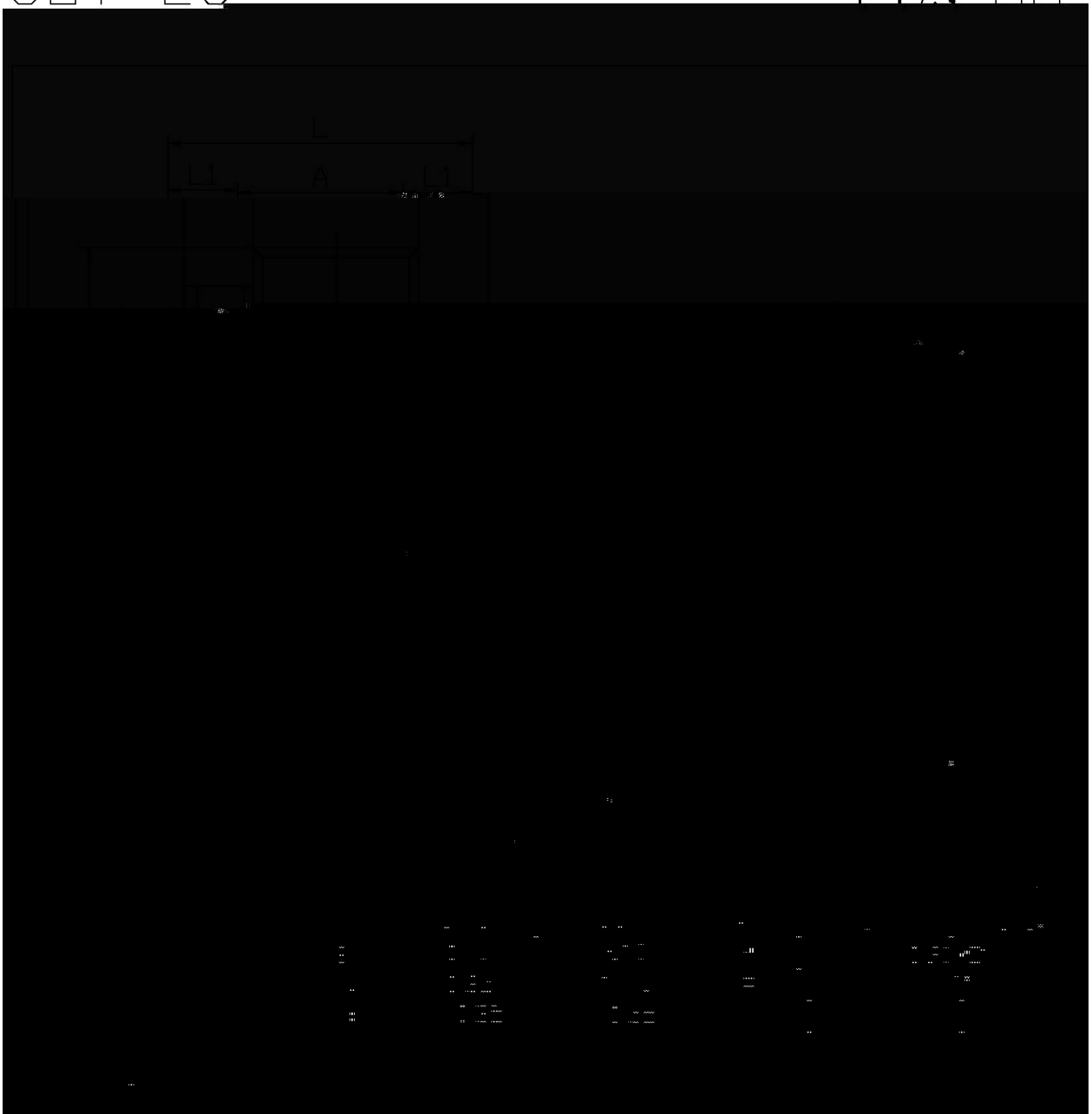
/ Electrical Characteristic Curve



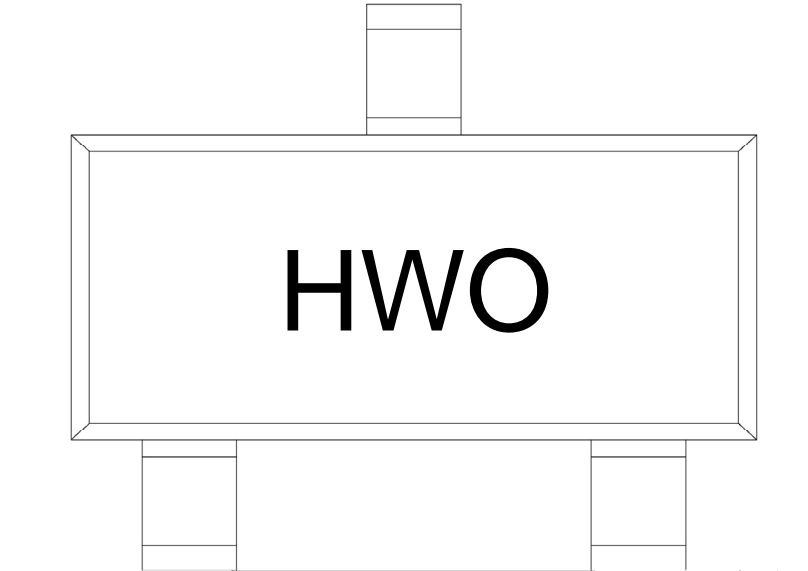
/ Package Dimensions

SOT-23

单位: mm



/ Marking Instructions



H

W

O h_{FE}

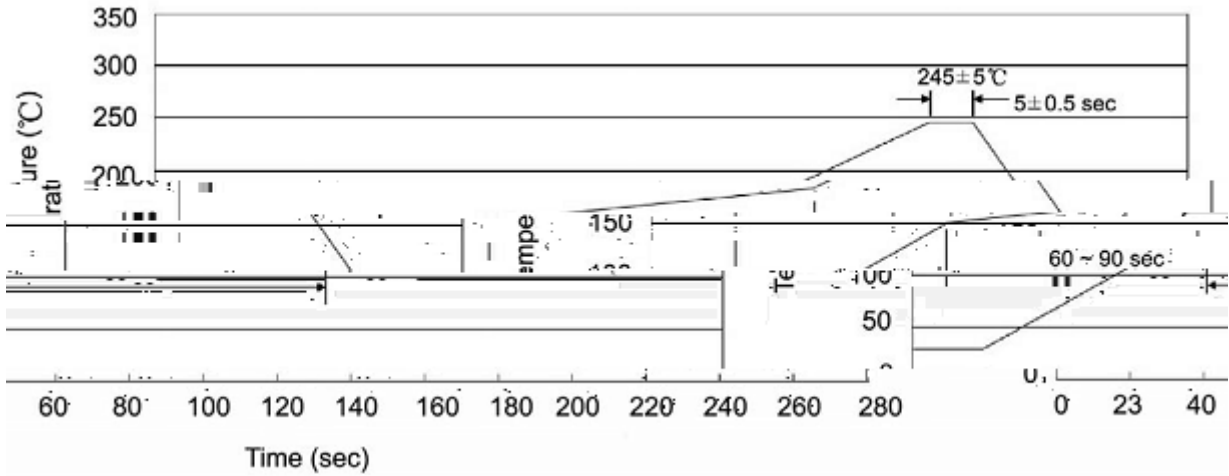
Note:

H Company Code

W Product Type

O h_{FE} Classifications Symbol

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|-----------------------------------------|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices